ON Semiconductor®

CMOS LSI

8-bit Microcontroller

16K-byte Flash ROM / 512-byte RAM / 36-pin

http://onsemi.com

Overview

The LC87F2416A is an 8-bit microcomputer that, centered around a CPU running at a minimum bus cycle time of 83.3ns, integrates on a single chip a number of hardware features such as 16K-byte Flash ROM (On-board-programmable), 512-byte RAM, an On-chip-debugger, sophisticated 16-bit timers/counters (may be divided into 8-bit timers), a 16-bit timer/counter (may be divided into 8-bit timers/counters or 8-bit PWMs), two 8-bit timers with a prescaler, a base timer serving as a time-of-day clock, a high-speed clock counter, a synchronous SIO interface (with automatic block transmission/reception capabilities), an asynchronous/synchronous SIO interface, a UART interface (full duplex), two 12-bit PWM channels, a 12-bit/8-bit 10-channel AD converter, a system clock frequency divider, an internal reset and a 20-source 10-vector interrupt feature.

Features

- ■Flash ROM
 - Capable of On-board-programming with wide range (2.2 to 5.5V) of voltage source.
 - Block-erasable in 128 byte units
 - 16384 × 8 bits (LC87F2416A)

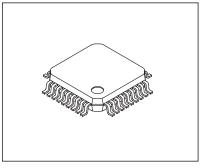
■RAM

- 512 × 9 bits (LC87F2416A)
- ■Minimum bus cycle time
 - 83.3ns (12MHz at $V_{DD} = 2.7V$ to 5.5V)
 - 100ns (10MHz at $V_{DD} = 2.2V$ to 5.5V)
 - 250ns (4MHz at $V_{DD} = 1.8V$ to 5.5V)

Note: The bus cycle time here refers to the ROM read speed.



- 250ns (12MHz at $V_{DD} = 2.7V$ to 5.5V)
- 300ns (10MHz at $V_{DD} = 2.2V$ to 5.5V)
- 750ns (4MHz at $V_{DD} = 1.8V$ to 5.5V)



QFP36

ORDERING INFORMATION

See detailed ordering and shipping information on page 28 of this data sheet.

^{*} This product is licensed from Silicon Storage Technology, Inc. (USA).

■Ports

• Normal withstand voltage I/O ports

Ports I/O direction can be designated in 1 bit units 16 (P1n, P20, P21, P30, P31, P70 to P73)

Ports I/O direction can be designated in 4 bit units 8 (P0n)

• Dedicated oscillator ports/input ports 2 (CF1/XT1, CF2/XT2)

• Reset pin $1(\overline{RES})$

• Power pins 3 (VSS1, VSS2, VDD1)

■Timers

• Timer 0: 16-bit timer/counter with a capture register.

Mode 0: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register) × 2 channels

Mode 1: 8-bit timer with an 8-bit programmable prescaler (with an 8-bit capture register) + 8-bit counter (with an 8-bit capture register)

Mode 2: 16-bit timer with an 8-bit programmable prescaler (with a 16-bit capture register)

Mode 3: 16-bit counter (with a 16-bit capture register)

• Timer 1: 16-bit timer/counter that supports PWM/toggle outputs

Mode 0: 8-bit timer with an 8-bit prescaler (with toggle outputs) + with an 8-bit prescaler 8-bit timer/counter (with toggle outputs)

Mode 1: 8-bit PWM with an 8-bit prescaler × 2 channels

Mode 2: 16-bit timer/counter with an 8-bit prescaler (with toggle outputs) (toggle outputs also possible from the lower-order 8 bits)

Mode 3: 16-bit timer with an 8-bit prescaler (with toggle outputs) (The lower-order 8 bits can be used as PWM.)

- Timer 6: 8-bit timer with a 6-bit prescaler (with toggle outputs)
- Timer 7: 8-bit timer with a 6-bit prescaler (with toggle outputs)
- Base timer
 - 1) The clock is selectable from the subclock (32.768kHz crystal oscillation), system clock, and timer 0 prescaler output.
 - 2) Interrupts are programmable in 5 different time schemes
 - 3) Base timer does not operate when selecting CF Oscillation circuit.

■High-speed clock counter

- 1) Capable of counting clocks with a maximum clock rate of 20MHz (at a main clock of 10MHz).
- 2) Capable of generating real-time output.

■SIO

- SIO0: 8-bit synchronous serial interface
 - 1) LSB first/MSB first mode selectable
 - 2) Built-in 8-bit baudrate generator (maximum transfer clock cycle = 4/3 tCYC)
 - 3) Automatic continuous data transmission (1 to 256 bits, specifiable in 1 bit units, suspension and resumption of data transmission possible in 1 byte units)
- SIO1: 8-bit asynchronous/synchronous serial interface
 - Mode 0: Synchronous 8-bit serial I/O (2- or 3-wire configuration, 2 to 512 tCYC transfer clocks)
 - Mode 1: Asynchronous serial I/O (half-duplex, 8 data bits, 1 stop bit, 8 to 2048 tCYC baudrates)
 - Mode 2: Bus mode 1 (start bit, 8 data bits, 2 to 512 tCYC transfer clocks)
 - Mode 3: Bus mode 2 (start detect, 8 data bits, stop detect)

■UART

- Full duplex
- 7/8/9 bit data bits selectable
- 1 stop bit (2-bit in continuous data transmission)
- Built-in baudrate generator
- ■AD converter: 12 bits/8 bits × 10 channels
 - 12 bits/8 bits AD converter resolution selectable
- ■PWM: Multifrequency 12-bit PWM × 2 channels
- ■Remote control receiver circuit (sharing pins with P73, INT3, and T0IN)
 - Noise rejection function (noise filter time constant selectable from 1 tCYC, 32 tCYC, and 128 tCYC)
- ■Clock output function
 - Capable of outputting selected oscillation clock 1/1, 1/2, 1/4, 1/8, 1/16, 1/32, or 1/64 as system clock.
 - Capable of outputting oscillation clock of sub clock.
- ■Watchdog timer
 - External RC watchdog timer
 - Interrupt and reset signals selectable

■Interrupts

- 20 sources, 10 vector addresses
 - 1) Provides three levels (low (L), high (H), and highest (X)) of multiplex interrupt control. Any interrupt requests of the level equal to or lower than the current interrupt are not accepted.
 - 2) When interrupt requests to two or more vector addresses occur at the same time, the interrupt of the highest level takes precedence over the other interrupts. For interrupts of the same level, the interrupt into the smallest vector address takes precedence.

No.	Vector Address	Level	Interrupt Source
1	00003H	X or L	INT0
2	0000BH	X or L	INT1
3	00013H	H or L	INT2/T0L/INT4
4	0001BH	H or L	INT3/INT5/base timer
5	00023H	H or L	ТОН
6	0002BH	H or L	T1L/T1H
7	00033H	H or L	SIO0/UART1 receive
8	0003BH	H or L	SIO1/UART1 transmit
9	00043H	H or L	ADC/T6/T7/PWM4, PWM5
10	0004BH	H or L	Port 0

- Priority levels X > H > L
- Of interrupts of the same level, the one with the smallest vector address takes precedence.
- ■Subroutine stack levels: 256levels (the stack is allocated in RAM.)

■High-speed multiplication/division instructions

16 bits × 8 bits
24 bits × 16 bits
16 bits ÷ 8 bits
24 bits ÷ 16 bits
(12 tCYC execution time)
(8 tCYC execution time)
24 bits ÷ 16 bits
(12 tCYC execution time)

■Oscillation circuits

RC oscillation circuit (internal)
 For system clock
 Frequency variable RC oscillation circuit (internal)
 For system clock

• CF oscillation circuit : For system clock, with internal Rf

• Crystal oscillation circuit : For low-speed system clock, with internal Rf

- 1) CF and crystal oscillation circuit have a shared terminal, and it is software selectable.
- 2) When reset, CF and Crystal oscillators stop operation. After reset is released, CF oscillator starts operation.

■System clock divider function

- Capable of running with low current consumption.
- The minimum instruction cycle selectable from 300ns, 600ns, 1.2μs, 2.4μs, 4.8μs, 9.6μs, 19.2μs, 38.4μs, and 76.8μs (at a main clock rate of 10MHz).

■Internal reset function

- Power-On-Reset (POR) function
 - 1) POR resets the system when the power supply voltage is applied.
 - 2) POR release level is selectable from 5 levels (1.55V, 1.72V, 2.00V, 2.37V, 2.65V) by option.
- Low Voltage Detection reset (LVD) function
 - 1) LVD used with POR resets the system when the supply voltage is applied and when it is lowered.
 - 2) LVD function is selectable from enable/disable and the reset level is selectable from 3 levels (1.90V, 2.25V, 2.50V) by option.

■Standby function

- HALT mode: Halts instruction execution while allowing the peripheral circuits to continue operation.
 - 1) Oscillation is not halted automatically.
 - 2) Canceled by a system reset or occurrence of an interrupt
- HOLD mode: Suspends instruction execution and the operation of the peripheral circuits.
 - 1) The CF, RC, and crystal oscillators automatically stop operation.
 - 2) There are three ways of resetting the HOLD mode.
 - (1) Setting the reset pin to the lower level.
 - (2) Setting at least one of the INT0, INT1, INT2, and INT4 pins to the specified level
 - (3) Having an interrupt source established at port 0
- X'tal HOLD mode: Suspends instruction execution and the operation of the peripheral circuits except the base timer.
 - 1) The CF and RC oscillators automatically stop operation.
 - 2) The state of crystal oscillation established when the X'tal HOLD mode is entered is retained.
 - 3) There are four ways of resetting the X'tal HOLD mode.
 - (1) Setting the reset pin to the low level
 - (2) Setting at least one of the INT0, INT1, INT2, and INT4 pins to the specified level
 - (3) Having an interrupt source established at port
 - (4) Having an interrupt source established in the base timer circuit

Note: X'tal HOLD mode can be used only when crystal oscillation is selected.

■Onchip-Debugger

- Supports software debugging with the IC mounted on the target board.
- For a small pin package, two-channel Onchip-Debugger port ((DBGP0(P0), DBGP1(P1)) are equipped.

■Flash data security

• Protects from illegal access to data in flash memory.

Note: Flash data security cannot guarantee perfect security.

■Package form

• QFP36 (7×7) : Lead-free type

■Development tools

• Onchip Debugger: TCB87 TypeB + LC87F2416A

■Flash ROM programming boards

_	- F - B	8
	Package	Programming boards
	QFP36 (7×7)	W87F24Q

■Flash ROM programmer

Maker		Model	Supported version (Note)	Device	
	Cinalo	AF9708/AF9709/AF9709B	Revision : After 02.60	LC87F2416A	
	Single	(including product of Ando Electric Co.,Ltd)			
Flash Support	0	AF9723 (Main body)			
Group, Inc.		(including product of Ando Electric Co.,Ltd)			
	Gang	AF9833 (Unit)			
		(including product of Ando Electric Co.,Ltd)			
Our Company		CKK Time D/ CANIVOTING)	Application Version : 1.03 or later	LC87F2416A	
Our Company		SKK Type-B(SANYOFWS)	Chip Data Version : 2.03 or later	LC0/F2410A	

For information about AF series, please contact the following:

Flash Support Group, Inc.

TEL: 053-459-1030 E-mail: sales@j-fsg.co.jp

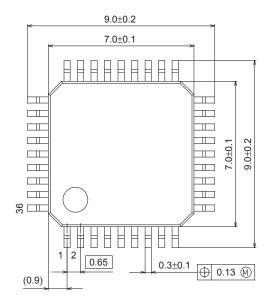
- ■Same package and pin assignment as mask ROM version.
 - 1) LC872400 series options can be set by using flash ROM data. Thus the board used for mass production can be used for debugging and evaluation without modifications.
 - 2) If the program for the mask ROM version is used, the usable ROM/RAM capacity is the same as the mask ROM version.

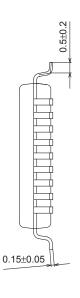
Package Dimensions

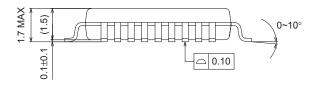
unit: mm

LQFP36 7x7 / QFP36

CASE 561AV ISSUE A



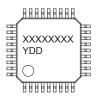


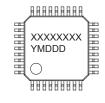


SOLDERING FOOTPRINT*

8.40 (Unit: mm) 07 8

GENERIC MARKING DIAGRAM*





XXXXX = Specific Device Code Y = Year

DD = Additional Traceability Data

XXXXX = Specific Device Code Y = Year

M = Month

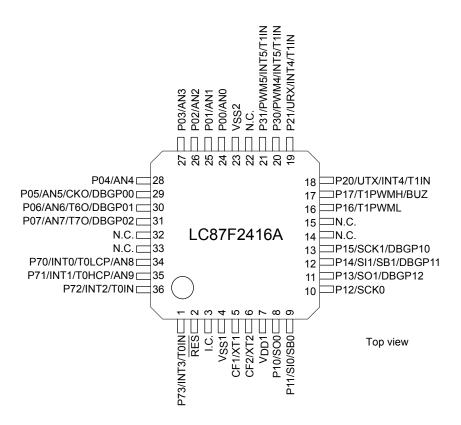
DDD = Additional Traceability Data

NOTE: The measurements are not to guarantee but for reference only.

^{*}This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present.

^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Pin Assignment



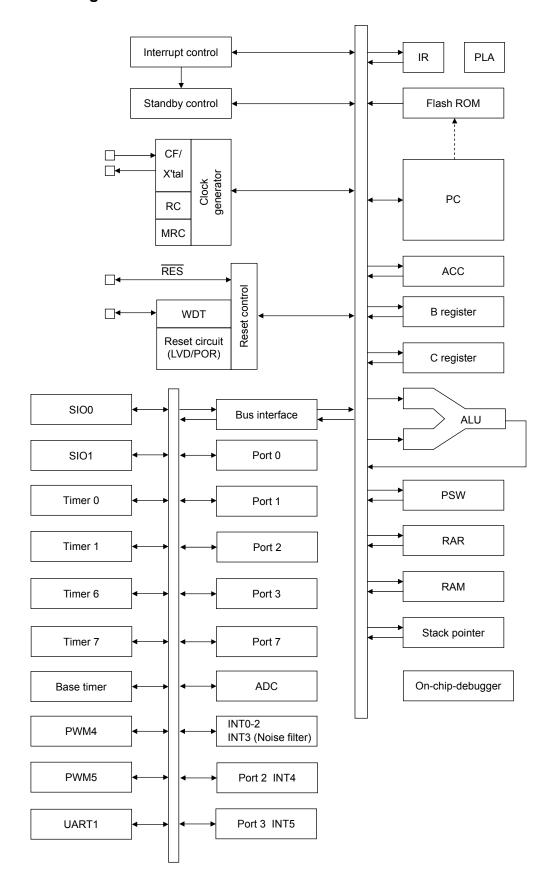
QFP36(7×7) "Lead-free Type"

QFP36	NAME
1	P73/INT3/T0IN
2	RES
3	I.C.
4	V _{SS} 1
5	CF1/XT1
6	CF2/XT2
7	V _{DD} 1
8	P10/S00
9	P11/SI0/SB0
10	P12/SCK0
11	P13/SO1/DBGP12
12	P14/SI1/SB1/DBGP11
13	P15/SCK1/DBGP10
14	N.C.
15	N.C.
16	P16/T1PWML
17	P17/T1PWMH/BUZ
18	P20/UTX/INT4/T1IN

QFP36	NAME
19	P21/URX/INT4/T1IN
20	P30/PWM4/INT5/T1IN
21	P31/PWM5/INT5/T1IN
22	N.C.
23	V _{SS} 2
24	P00/AN0
25	P01/AN1
26	P02/AN2
27	P03/AN3
28	P04/AN4
29	P05/AN5/CKO/DBGP00
30	P06/AN6/T6O/DBGP01
31	P07/AN7/T7O/DBGP02
32	N.C.
33	N.C.
34	P70/INT0/T0LCP/AN8
35	P71/INT1/T0HCP/AN9
36	P72/INT2/T0IN

Note: The I.C. (Internally-Connected) and N.C. (Non-Connection) terminal must be kept open.

System Block Diagram



Pin Function Chart

Pin Name	I/O			De	scription			Option		
V _{SS} 1, V _{SS} 2	-	-power supply pins	3					No		
V _{DD} 1	-	+power supply pin	+power supply pin							
Port 0	I/O	• 8-bit I/O port						Yes		
P00 to P07		I/O specifiable in	4 bit units							
1 00 10 1 01		Pull-up resistors can be turned on and off in 4 bit units.								
		HOLD reset input								
		Port 0 interrupt input								
		Pin functions								
		P05: System clo	ck output							
		P06: Timer 6 tog	gle output							
		P07: Timer 7 tog								
		P00 (AN0) to P0		-						
			o P07 (DBG	P02): On-chip-de	bugger 0 port					
Port 1	I/O	• 8-bit I/O port						Yes		
P10 to P17		I/O specifiable in								
		Pull-up resistors	can be turne	d on and off in 1	bit units.					
		• Pin functions								
		P10: SIO0 data output P11: SIO0 data input/bus I/O								
		P12: SIO0 data i	•							
			P13: SIO1 data output P14: SIO1 data input/bus I/O							
		P15: SIO1 clock I/O								
		P16: Timer 1PWML output								
		P17: Timer 1PW	-	eeper output						
			-	P12): On-chip-de	bugger 1 port					
Port 2	I/O	• 2-bit I/O port	,	•				Yes		
P20 to P21	1	• I/O specifiable in 1 bit units								
		Pull-up resistors	can be turne	d on and off in 1	bit units.					
		Pin functions								
		P20: UART trans	smit							
		P21: UART rece								
		P20 to P21: INT	4 input/HOLI	O reset input/time	r 1 event input					
			•	e input/timer 0H c	apture input					
		Interrupt acknowle	dge type	1	T	Т	T 1			
			Rising	Falling	Rising &	H level	L level			
				_	Falling					
		INT4	0	0	0	X	×			
Port 3	I/O	• 2-bit I/O port						Yes		
P30 to P31		I/O specifiable in								
		Pull-up resistors	can be turne	d on and off in 1	bit units.					
		Pin functions								
		P30:PWM4 outp								
		P31:PWM5 outp								
		P30 to P31: INT:	•	•	•					
			-	e input/timer 0H c	apture input					
		Interrupt acknowle	age type	1	District					
			Rising	Falling	Rising &	H level	L level			
	1	1 1			Falling			1		
		INT5	0	0	0	×	×			

Continued on next page.

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Pin Name	I/O			Desc	ription			Option
Port 7	I/O	• 4-bit I/O port						No
P70 to P73	1	• I/O specifiable in 1 bit units						
		 Pull-up resisto 	rs can be turned o	on and off in 1 bit	units.			
		Pin functions						
		P70: INT0 inp	ut/HOLD reset inp	out/timer 0L captu	re input			
		/watchdo	g timer output					
		P71: INT1 inp	ut/HOLD reset inp	out/timer 0H captu	ıre input			
			ut/HOLD reset inp	out/timer 0 event	nput			
		/timer 0L	capture input					
		-	ut (with noise filte	r)/timer 0 event ir	put			
			I capture input					
		P70 (AN8), P71 (AN9): AD converter input						
		Interrupt acknow	vledge type		1	1		
			Rising	Falling	Rising & Falling	H level	L level	
		INT0	0	0	×	0	0	
		INT1	0	0	×	0	0	
		INT2	0	0	0	×	×	
		INT3	0	0	0	×	×	
RES	I/O	Reset Input pin	and Internal reset	t output pin				No
CF1/XT1	Input		ator or 32.768kH		r input pin			No
01 1/2(11	IIIpat	Pin function	10101 01 02.7 00Ki ii	z oryotar ocomato	input pin			
		General-purpose input port						
				e input port and o	connected to Vee	1 if not to be us	ed.	
CF2/XT2	I/O	Must be set for General-purpose input port and connected to VSS1 if not to be used. I/O • Ceramic resonator or 32.768kHz crystal oscillator output pin					No	
		• Pin function						
			General-purpose input port					
			r General-purpos	e input port and o	onnected to Voc	1 if not to be us	ad	

Port Output Types

The table below lists the types of port outputs and the presence/absence of a pull-up resistor.

Data can be read into any input port even if it is in the output mode.

Port Name	Option selected in units of	Option type	Output type	Pull-up resistor
P00 to P07	1 bit	1	CMOS	Programmable (Note 1)
		2	Nch-open drain	No
P10 to P17	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P20 to P21	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P30 to P31	1 bit	1	CMOS	Programmable
		2	Nch-open drain	Programmable
P70	-	No	Nch-open drain	Programmable
P71 to P73	-	No	CMOS	Programmable

Note1: Programmable pull-up resistors and selection of low-impedance-pull-up/high-impedance-pull-up for port 0 are controlled on lower four bits and upper four bits (P00 to P03, P04 to P07).

Note: VSS1 and VSS2 should connect to each other and they should also be grounded.

Onchip Debugger pin connection requirements

Refer to the separate documents, "RD87 Onchip Debugger Installation Manual" and "LC87200series pin connection requirements Manual", for the requirements on Onchip Debugger pin connections.

1. Absolute Maximum Ratings at $Ta=25^{\circ}C,\,V_{SS}1=V_{SS}2=0V$

	Parameter	Symbol	Pin/Remarks	Conditions		Specification min. typ. max.			
	Farameter	Symbol	Fill/Remarks	Conditions	V _{DD} [V]			unit	
	ximum supply tage	V _{DD} MAX	V _{DD} 1			-0.3	-	+6.5	
Inp	ut voltage	VI	CF1			-0.3	-	V _{DD} +0.3	V
	ut/output tage	V _{IO}	Ports 0, 1, 2, 3 Port 7			-0.3	-	V _{DD} +0.3	V
	Peak output current	IOPH(1)	Ports 0, 1, 2, 3	CMOS output select Per 1 applicable pin		-10			
Ħ		IOPH(2)	Ports P71 to P73	Per 1 applicable pin		-5			
High level output current	Mean output current	IOMH(1)	Ports 0, 1, 2, 3	CMOS output select Per 1 applicable pin		-7.5			
ontp	(Note 1-1)	IOMH(2)	Ports P71 to P73	Per 1 applicable pin		-3			
vel c	Total output	ΣΙΟΑΗ(1)	Ports P71 to P73	Total of all applicable pins		-10			
Jh le	current	ΣΙΟΑΗ(2)	Ports P10 to P14	Total of all applicable pins		-20			
Hig		ΣΙΟΑΗ(3)	Ports P15 to P17 Ports 0, 2, 3	Total of all applicable pins		-20			
		ΣΙΟΑΗ(4)	Ports 0, 1, 2, 3	Total of all applicable pins		-25			
	Peak output current	IOPL(1)	Ports P02 to P07 Ports 1, 2, 3	Per 1 applicable pin				20	mA
		IOPL(2)	Ports P00, P01	Per 1 applicable pin				30	
		IOPL(3)	Port 7	Per 1 applicable pin				10	
Low level output current	Mean output current	IOML(1)	Ports P02 to P07 Ports 1, 2, 3	Per 1 applicable pin				15	
:put	(Note 1-1)	IOML(2)	Ports P00, P01	Per 1 applicable pin				20	
l out		IOML(3)	Port 7	Per 1 applicable pin				7.5	
leve	Total output	ΣIOAL(1)	Port 7	Total of all applicable pins				15	
Low	current	ΣIOAL(2)	Ports 0	Total of all applicable pins				40	
		ΣIOAL(3)	Ports P10 to P14	Total of all applicable pins				35	
		ΣIOAL(4)	Ports 1, 2, 3	Total of all applicable pins				40	
		ΣIOAL(5)	Ports 0, 1, 2, 3	Total of all applicable pins				70	
Po	wer dissipation	Pd max(1)	QFP36	Ta=-40 to +85°C Package only				120	
		Pd max(2)		Ta=-40 to +85°C Package with thermal resistance board (Note 1-2)				275	mW
	erating ambient	Topg				-40	-	+85	20
	orage ambient	Tstg				-55	-	+125	°C

Note 1-1: The mean output current is a mean value measured over 100ms.

Note 1-2: SEMI standards thermal resistance board (size: 76.1×114.3×1.6tmm, glass epoxy) is used.

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

2. Allowable Operating Conditions at Ta = -40 to +85°C, $V_{SS}1$ = $V_{SS}2$ = 0V

Doromotor	Symbol	Pin/Remarks	Conditions			Specifi	cation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min.	typ.	max.	unit
Operating	V _{DD} (1)	V _{DD} 1	0.245μs ≤ tCYC ≤ 200μs		2.7		5.5	
supply voltage	V _{DD} (2)		0.294μs ≤ tCYC ≤ 200μs		2.2		5.5	
(Note 2-1)	V _{DD} (3)		$0.735\mu s \le tCYC \le 200\mu s$		1.8		5.5	
Memory sustaining supply voltage	VHD	V _{DD} 1	RAM and register contents sustained in HOLD mode.		1.6			
High level input voltage	V _{IH} (1)	Ports 1, 2, 3 P71 to P73 P70 port input /interrupt side		1.8 to 5.5	0.3V _{DD} +0.7		V _{DD}	
	V _{IH} (2)	Ports 0		1.8 to 5.5	0.3V _{DD} +0.7		V _{DD}	
	V _{IH} (3)	Port 70 watchdog timer side		1.8 to 5.5	0.9V _{DD}		V _{DD}	V
	V _{IH} (4)	CF1, RES		1.8 to 5.5	0.75V _{DD}		V_{DD}	
Low level input voltage	V _{IL} (1)	Ports 1, 2, 3 P71 to P73		4.0 to 5.5	V _{SS}		0.1V _{DD} +0.4	
		P70 port input /interrupt side		1.8 to 4.0	V _{SS}		0.2V _{DD}	
	V _{IL} (2)	Ports 0		4.0 to 5.5	V _{SS}		0.15V _{DD} +0.4	
				1.8 to 4.0	V _{SS}		0.2V _{DD}	
	V _{IL} (3)	Port 70 watchdog timer side		1.8 to 5.5	V _{SS}		0.8V _{DD} -1.0	
	V _{IL} (4)	CF1, RES		1.8 to 5.5	V_{SS}		0.25V _{DD}	
Instruction cycle	tCYC			2.7 to 5.5	0.245		200	
time	(Note 2-2)			2.2 to 5.5	0.294		200	μs
(Note 2-1)				1.8 to 5.5	0.735		200	
External system	FEXCF	CF1	CF2 pin open	2.7 to 5.5	0.1		12	
clock frequency			 System clock frequency division ratio = 1/1 External system clock duty = 50±5% 	1.8 to 5.5	0.1		4	
			CF2 pin open	3.0 to 5.5	0.2		24.4	
			 System clock frequency division ratio = 1/2 External system clock duty = 50±5% 	2.0 to 5.5	0.1		8	MHz
Oscillation frequency range	FmCF(1)	CF1, CF2	12MHz ceramic oscillation See Fig. 1.	2.7 to 5.5		12		
(Note 2-3)	FmCF(2)	CF1, CF2	10MHz ceramic oscillation See Fig. 1.	2.2 to 5.5		10		
	FmCF(3)	CF1, CF2	4MHz ceramic oscillation See Fig. 1.	1.8 to 5.5		4		
	FmRC		Internal RC oscillation	1.8 to 5.5	0.3	1.0	2.0	
	FmMRC		Frequency variable RC oscillation source oscillation	2.7 to 5.5		16		
	FsX'tal(1)	XT1, XT2	32.768kHz crystal oscillation See Fig. 2.	1.8 to 5.5		32.768		kHz

Note 2-1: V_{DD} must be held greater than or equal to 2.2V in the flash ROM onboard programming mode.

Note 2-3: See Tables 1 and 2 for the oscillation constants.

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

Note 2-2: Relationship between tCYC and oscillation frequency is 3/FmCF at a division ratio of 1/1 and 6/FmCF at a division ratio of 1/2.

3. Electrical Characteristics at $Ta = -40 \text{ to } +85^{\circ}\text{C}, V_{SS}1 = V_{SS}2 = 0\text{V}$

Parameter	Symbol	Pin/Remarks	Conditions			Specific	ation	
Farameter	Syllibol	Fill/Remarks	Conditions	V _{DD} [V]	min.	typ.	max.	unit
High level input current	l _{IH} (1)	Ports 0, 1, 2, 3 Ports 7 RES	Output disabled Pull-up resistor off V _{IN} =V _{DD} (Including output Tr's off leakage current)	1.8 to 5.5			1	
	I _{IH} (2)	CF1	V _{IN} =V _{DD}	1.8 to 5.5			15	
Low level input current	I _{IL} (1)	Ports 0, 1, 2, 3 Ports 7 RES	Output disabled Pull-up resistor off VIN=VSS (Including output Tr's off leakage current)	1.8 to 5.5	-1			μА
	I _{IL} (2)	CF1	V _{IN} =V _{SS}	1.8 to 5.5	-15			
High level output	V _{OH} (1)	Ports 0, 1, 2	I _{OH} =-1mA	4.5 to 5.5	V _{DD} -1			
voltage	V _{OH} (2)	P71 to P73	I _{OH} =-0.35mA	2.7 to 5.5	V _{DD} -0.4			
	V _{OH} (3)		I _{OH} =-0.15mA	1.8 to 5.5	V _{DD} -0.4			
	V _{OH} (4)	Port 3	I _{OH} =-6mA	4.5 to 5.5	V _{DD} -1			
	V _{OH} (5)	(Note 3-1)	I _{OH} =-1.4mA	2.7 to 5.5	V _{DD} -0.4			
	V _{OH} (6)		I _{OH} =-0.8mA	1.8 to 5.5	V _{DD} -0.4			
Low level output	V _{OL} (1)	Ports 0, 1, 2, 3	I _{OL} =10mA	4.5 to 5.5			1.5	
voltage	V _{OL} (2)		I _{OL} =1.4mA	2.7 to 5.5			0.4	V
	V _{OL} (3)		I _{OL} =0.8mA	1.8 to 5.5			0.4	
	V _{OL} (4)	Port 7	I _{OL} =1.4mA	2.7 to 5.5			0.4	
	V _{OL} (5)		I _{OL} =0.8mA	1.8 to 5.5			0.4	
	V _{OL} (6)	P00, P01	I _{OL} =25mA	4.5 to 5.5			1.5	
	V _{OL} (7)		I _{OL} =4mA	2.7 to 5.5			0.4	
	V _{OL} (8)		I _{OL} =2mA	1.8 to 5.5			0.4	
Pull-up resistance	Rpu(1)	Ports 0, 1, 2, 3	V _{OH} =0.9V _{DD}	4.5 to 5.5	15	35	80	
	Rpu(2)	Port 7	When Port 0 selected low-impedance pull-up.	1.8 to 4.5	18	50	230	kΩ
	Rpu(3)	Ports 0	High-impedance pull-up.	1.8 to 5.5	100	210	400	
Hysteresis voltage	VHYS(1)	Ports 1, 2, 3, 7,		2.7 to 5.5		0.1V _{DD}		V
	VHYS(2)	RES		1.8 to 2.7		0.07V _{DD}		V
Pin capacitance	СР	All pins	For pins other than that under test: VIN=VSS f=1MHz Ta=25°C	1.8 to 5.5		10		pF

Note 3-1: High level output current on port 3 flows as 4 to 6 times as that of mask ROM version (LC872416A/12A/08A).

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Serial I/O Characteristics at Ta = -40 to +85°C, $V_{SS}1 = V_{SS}2 = 0V$

4-1. SIO0 Serial I/O Characteristics (Note 4-1-1)

		Parameter	Symbol	Pin/Remarks	Conditions			Speci	fication	
	F	rarameter	Symbol	Pili/Remarks	Conditions	V _{DD} [V]	min.	typ.	max.	unit
		Frequency	tSCK(1)	SCK0(P12)	• See Fig. 5.		2			
		Low level	tSCKL(1)				1			
	충	pulse width High level	tSCKH(1)	-			1			
	Input clock	pulse width	tSCKHA(1)	-	Continuous data	1.8 to 5.5				10)10
	Inp		(1)		transmission/reception					tCYC
					mode		4			
ck					• See Fig. 5.					
Serial clock		Frequency	tSCK(2)	SCK0(P12)	(Note 4-1-2) • CMOS output selected		4/3			
Seri		Low level	tSCKL(2)	,	• See Fig. 5.					
		pulse width	` '					1/2		tSCK
	Output clock	High level	tSCKH(2)				1/2			1.0011
	put c	pulse width	tSCKHA(2)	-	Continuous data	1.8 to 5.5				
	Out		tooki iA(2)		transmission/reception				tSCKH(2)	
					mode		tSCKH(2) +2tCYC		+(10/3)	tCYC
					CMOS output selected		121010		tCYC	
	Da	ta setup time	tsDI(1)	SB0(P11),	See Fig. 5. Must be specified with					
nt	-	ta ootap iiiio	(1)	SI0(P11)	respect to rising edge of		0.05			
ıl inp					SIOCLK.	1.8 to 5.5				
Serial input	Da	ta hold time	thDI(1)		• See Fig. 5.		0.05			
							0.05			
		Output delay	tdD0(1)	SO0(P10),	Continuous data					
	ос	time		SB0(P11)	transmission/reception				(1/3)tCYC	
	Input clock				mode (Note 4-1-3)				+0.08	μs
ıtput	Serial output		tdD0(2)	1	Synchronous 8-bit mode				1tCYC	
al or					(Note 4-1-3)	1.8 to 5.5			+0.08	
Seri	Š		tdD0(3)		(Note 4-1-3)					
	ıt clo								(1/3)tCYC	
	Output clock								+0.08	
	J									

Note 4-1-1: These specifications are theoretical values. Add margin depending on its use.

Note 4-1-2: To use serial-clock-input in continuous trans/rec mode, a time from SI0RUN being set when serial clock is "H" to the first negative edge of the serial clock must be longer than tSCKHA.

Note 4-1-3: Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 5.

4-2. SIO1 Serial I/O Characteristics (Note 4-2-1)

	-	Parameter	Symbol	Pin/Remarks	Conditions			Speci	fication		
	Г	arameter	Symbol	FIII/Remarks	Conditions	V _{DD} [V]	min.	typ.	max.	unit	
		Frequency	tSCK(3)	SCK1(P15)	• See Fig. 5.		2				
	Input clock	Low level pulse width	tSCKL(3)			1.8 to 5.5	1			tCYC	
Serial clock	dul	High level pulse width	tSCKH(3)				1			ICTC	
erial	~	Frequency	tSCK(4)	SCK1(P15)	CMOS output selected		2				
S	S Low level pulse width		tSCKL(4)		• See Fig. 5.	5. 1.8 to 5.5		1/2		tSCK	
	Outp	High level pulse width	tSCKH(4)					1/2			
Serial input	Da	ita setup time	tsDI(2)	SB1(P14), SI1(P14)	Must be specified with respect to rising edge of SIOCLK.	401.55	0.05				
Serial	Da	ita hold time	thDI(2)		• See Fig. 5.	1.8 to 5.5	0.05				
Serial output	Ou	itput delay time	tdD0(4)	SO1(P13), SB1(P14)	Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 5.	1.8 to 5.5			(1/3)tCYC +0.08	μs	

Note 4-2-1: These specifications are theoretical values. Add margin depending on its use.

5. Pulse Input Conditions at Ta = -40 to +85°C, $V_{SS}1 = V_{SS}2 = 0V$

Parameter	Cumbal	Pin/Remarks	Conditions			Specif	ication	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min.	typ.	max.	unit
High/low level	tPIH(1)	INT0(P70),	Interrupt source flag can be set.					
pulse width	tPIL(1)	INT1(P71),	Event inputs for timer 0 or 1 are					
		INT2(P72),	enabled.	1.8 to 5.5	1			
		INT4(P20 to P21),						
		INT5(P30 to P31)						
	tPIH(2)	INT3(P73) when	Interrupt source flag can be set.					
	tPIL(2)	noise filter time	Event inputs for timer 0 are enabled.	1.8 to 5.5	2			40)(0
		constant is 1/1						tCYC
	tPIH(3)	INT3(P73) when	Interrupt source flag can be set.					
	tPIL(3)	noise filter time	Event inputs for timer 0 are enabled.	1.8 to 5.5	64			
		constant is 1/32						
	tPIH(4)	INT3(P73) when	Interrupt source flag can be set.					
	tPIL(4)	noise filter time	Event inputs for timer 0 are enabled.	1.8 to 5.5	256			
		constant is 1/128						
	tPIL(5)	RES	External reset input mode.	1 0 to E E	200			
			Resetting is enabled.	1.8 to 5.5	200			μs

6. AD Converter Characteristics at $V_{SS}1 = V_{SS}2 = 0V$

<12-bit AD Converter Mode / Ta = -40 to +85°C>

Danamatan	Oh al	Dia/Damada	Conditions			Speci	fication	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min.	typ.	max.	unit
Resolution	N	AN0(P00) to		2.4 to 5.5		12		bit
Absolute	ET	AN7(P07)	(Note 6-1)	3.0 to 5.5			±16	
accuracy	AN9(P71)	` '	(Note 6-1) • Ta=-10 to +50°C	2.4 to 3.6			±20	
Conversion time	TCAD		See Conversion time calculation	4.0 to 5.5	32		115	
			formulas. (Note 6-2)	3.0 to 5.5	64		115	
			See Conversion time calculation formulas. (Note 6-2) Ta=-10 to +50°C	2.4 to 3.6	410		425	μs
Analog input voltage range	VAIN			2.4 to 5.5	V _{SS}		V_{DD}	٧
Analog port input	IAINH		VAIN=V _{DD}	2.4 to 5.5			1	
current	IAINL		VAIN=V _{SS}	2.4 to 5.5	-1			μΑ

<8-bit AD Converter Mode / Ta = -40 to +85°C>

Parameter	Symbol	Pin/Remarks	Conditions			Specif	fication	
Farameter	Symbol	Fill/Remarks	Conditions	V _{DD} [V]	min.	typ.	max.	unit
Resolution	N	AN0(P00) to		2.4 to 5.5		8		bit
Absolute accuracy	ET	AN7(P07) AN8(P70)	(Note 6-1)	2.4 to 5.5			±1.5	LSB
Conversion time	TCAD	AN9(P71)	See Conversion time calculation	4.0 to 5.5	20		90	
			formulas. (Note 6-2)	3.0 to 5.5	40		90	
			See Conversion time calculation formulas. (Note 6-2) Ta=-10 to +50°C	2.4 to 3.6	250		265	μs
Analog input voltage range	VAIN			2.4 to 5.5	V _{SS}		V _{DD}	V
Analog port input	IAINH		VAIN=V _{DD}	2.4 to 5.5			1	
current	IAINL	1	VAIN=V _{SS}	2.4 to 5.5	-1			μΑ

- Note 6-1: The quantization error ($\pm 1/2$ LSB) must be excluded from the absolute accuracy. The absolute accuracy must be measured in the microcontroller's state in which no I/O operations occur at the pins adjacent to the analog input channel.
- Note 6-2: The conversion time refers to the period from the time an instruction for starting a conversion process till the time the conversion results register(s) are loaded with a complete digital conversion value corresponding to the analog input value.

The conversion time is 2 times the normal-time conversion time when:

- The first AD conversion is performed in the 12-bit AD conversion mode after a system reset.
- The first AD conversion is performed after the AD conversion mode is switched from 8-bit to 12-bit conversion mode.

Conversion time calculation formulas:

12-bits AD Converter Mode : TCAD (Conversion time) = $((52/(\text{division ratio}))+2) \times (1/3) \times \text{tCYC}$ 8-bits AD Converter Mode : TCAD (Conversion time) = $((32/(\text{division ratio}))+2) \times (1/3) \times \text{tCYC}$

External oscillation	Operating supply voltage range	I System division ratio I Cycle time I AD division ratio I		AD conve (TC	rsion time AD)	
(FmCF)	(V _{DD})	(SYSDIV)	(tCYC)	(ADDIV)	12bit AD	8bit AD
OF 40MH-	4.0V to 5.5V	1/1	250ns	1/8	34.8μs	21.5µs
CF-12MHz	3.0V to 5.5V	1/1	250ns	1/16	69.5μs	42.8µs
05.40141	4.0V to 5.5V	1/1	300ns	1/8	41.8µs	25.8µs
CF-10MHz	3.0V to 5.5V	1/1	300ns	1/16	83.4µs	51.4μs
OF AMUL	3.0V to 5.5V	1/1	750ns	1/8	104.5μs	64.5μs
CF-4MHz	2.4V to 3.6V	1/1	750ns	1/32	416.5µs	256.5μs

7. Power-on reset (POR) Characteristics at $Ta = -40 \text{ to } +85^{\circ}\text{C}$, $V_{SS}1 = V_{SS}2 = 0\text{V}$

						Specif	fication	
Parameter	Symbol	Pin/Remarks	Conditions	Option selected voltage	min.	typ.	max.	unit
POR release	PORR		Select from option.	1.55V	1.38	1.55	1.72	
voltage			(Note 7-1)	1.72V	1.54	1.72	1.90	
				2.00V	1.81	2.00	2.19	
				2.37V	2.12	2.37	2.62	V
				2.65V	2.39	2.65	2.91	
Detection voltage unknown state	POUKS		• See Fig. 7. (Note 7-2)			0.7	0.95	
Power supply rise time	PORIS		Power supply rise time from 0V to 1.4V.				100	ms

Note 7-1: The POR release level can be selected out of 5 levels only when the LVD reset function is disabled.

Note 7-2: POR is in an unknown state before transistors start operation.

8. Low voltage detection reset (LVD) Characteristics at Ta = -40 to +85°C, $V_{SS}1 = V_{SS}2 = 0V$

						Specifi	cation	
Parameter	Symbol	Pin/Remarks	Conditions	Option selected voltage	min.	typ.	max.	unit
LVD reset	LVDET		Select from option.	1.90V	1.72	1.90	2.08	
Voltage			(Note 8-1)	2.25V	2.03	2.25	2.47	
• See Fig. 8. (Note 8-2)			(Note 8-3)	2.50V	2.26	2.50	2.74	
LVD hysteresys width	LVHYS			1.90V		LVDET ×0.054		
				2.25V		LVDET ×0.062		V
				2.50V		LVDET ×0.065		
Detection voltage unknown state	LVUKS		• See Fig. 8. (Note 8-4)			0.7	0.95	
Low voltage detection minimum Width (Reply sensitivity)	TLVDW		• See Fig. 9.		0.2			ms

Note 8-1: The LVD reset level can be selected out of 3 levels only when the LVD reset function is enabled.

Note 8-2: LVD reset voltage specification values do not include hysteresis voltage.

Note 8-3: LVD reset voltage may exceed its specification values when port output state changes and/or when a large current flows through port.

Note 8-4: LVD is in an unknown state before transistors start operation.

9. Consumption Current Characteristics at Ta = -40 to +85°C, $V_{SS}1$ = $V_{SS}2$ = 0V

Parameter	Symbol	Pin/Remarks	Conditions			Specif	fication		
r arameter	Зуппон	FIII/Remarks	Conditions	V _{DD} [V]	min.	typ.	Max.	unit	
Normal mode consumption current (Note 9-1)	IDDOP(1)	V _{DD} 1	FmCF=12MHz ceramic oscillation mode System clock set to 12MHz side Internal RC oscillation stopped.	2.7 to 5.5		8.3	15.1		
(Note 9-2)			Frequency variable RC oscillation stopped. 1/1 frequency division ratio	2.7 to 3.6		4.8	8.7		
	IDDOP(2)		CF1=24MHz external clock System clock set to CF1 side Internal RC oscillation stopped.	3.0 to 5.5		9	16.2		
			Frequency variable RC oscillation stopped. 1/2 frequency division ratio	3.0 to 3.6		5.2	8.7		
	IDDOP(3)		FmCF=10MHz ceramic oscillation mode System clock set to 10MHz side	2.2 to 5.5		7.3	13.8		
			Internal RC oscillation stopped. Frequency variable RC oscillation stopped. 1/1 frequency division ratio	2.2 to 3.6		4.3	8.3		
	IDDOP(4)		FmCF=4 MHz ceramic oscillation mode System clock set to 4MHz side	1.8 to 5.5		3.6	7.8	mA	
				Internal RC oscillation stopped. Frequency variable RC oscillation stopped. 1/1 frequency division ratio	1.8 to 3.6		2.5	4.9	
	IDDOP(5)		FsX'tal=32.768kHz crystal oscillation mode System clock set to internal RC oscillation.	1.8 to 5.5		0.7	2.4		
			Frequency variable RC oscillation stopped. 1/2 frequency division ratio	1.8 to 3.6		0.4	1.2		
	IDDOP(6)		FsX'tal=32.768kHz crystal oscillation mode Internal RC oscillation stopped. System clock set to 1MHz with	1.8 to 5.5		1.3	2.8		
			Frequency variable RC oscillation • 1/2 frequency division ratio	1.8 to 3.6		0.8	1.6		
	IDDOP(7)		FsX'tal=32.768kHz crystal oscillation mode System clock set to 32.768kHz side	1.8 to 5.5		39	139		
	IDDOP(8)	Internal RC oscillation stopped. Frequency variable RC oscillation stopped. 1/2 frequency division ratio FsX'tal=32.768kHz crystal oscillation mode System clock set to 32.768kHz side Internal RC oscillation stopped. Frequency variable RC	Frequency variable RC oscillation stopped.	1.8 to 3.6		17	66		
			5.0		39	101	μΑ		
			3.3		17	47			
			oscillation stopped. • 1/2 frequency division ratio • Ta=-10 to +50°C	2.5		10	29		

Note 9-1: Values of the consumption current do not include current that flows into the output transistors and internal pull-up resistors.

Note 9-2: The consumption current values do not include operational current of LVD function if not specified.

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Parameter	Symbol	Pin/remarks	Conditions			Specif	cation	
	2,201		00.10.10	V _{DD} [V]	min.	typ.	max.	unit
HALT mode consumption current (Note 9-1)	IDDHALT(1)	V _{DD} 1	HALT mode FmCF=12MHz ceramic oscillation mode System clock set to 12MHz side	2.7 to 5.5		3.4	6.2	
(Note 9-2)			Internal RC oscillation stopped. Frequency variable RC oscillation stopped. 1/1 frequency division ratio	2.7 to 3.6		1.8	3.1	
	IDDHALT(2)		HALT mode CF1=24MHz external clock System clock set to CF1 side	3.0 to 5.5		4.9	8.6	
			Internal RC oscillation stopped. Frequency variable RC oscillation stopped. 1/2 frequency division ratio	3.0 to 3.6		2.3	3.8	
	IDDHALT(3)		HALT mode FmCF=10MHz ceramic oscillation mode System clock set to 10MHz side	2.2 to 5.5		2.9	5.6	
			Internal RC oscillation stopped. Frequency variable RC oscillation stopped. 1/1 frequency division ratio	2.2 to 3.6		1.5	2.8	
	IDDHALT(4)		HALT mode FmCF=4MHz ceramic oscillation mode System clock set to 4MHz side	1.8 to 5.5		1.5	3.7	mA
			Internal RC oscillation stopped. Frequency variable RC oscillation stopped. 1/1 frequency division ratio	1.8 to 3.6		0.7	1.6	
	IDDHALT(5)		HALT mode FsX'tal=32.768kHz crystal oscillation mode System clock set to internal RC	1.8 to 5.5		0.5	1.4	
			oscillation • Frequency variable RC oscillation stopped. • 1/2 frequency division ratio	1.8 to 3.6		0.2	0.6	
	IDDHALT(6)		HALT mode FsX'tal=32.768kHz crystal oscillation mode Internal RC oscillation stopped.	1.8 to 5.5		T.B.D	T.B.D	
			System clock set to 1MHz with Frequency variable RC oscillation 1/2 frequency division ratio	1.8 to 3.6		T.B.D	T.B.D	
	IDDHALT(7)		HALT mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 32.768kHz side	1.8 to 5.5		25	112	
			Internal RC oscillation stopped Frequency variable RC oscillation stopped. 1/2 frequency division ratio	1.8 to 3.6		8.5	56	μА

Note 9-1: Values of the consumption current do not include current that flows into the output transistors and internal pull-up resistors.

Note 9-2: The consumption current values do not include operational current of LVD function if not specified.

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Darameter	Symbol	Pin/remarks	Conditions			Specif	cation	on			
Parameter	Symbol	Pin/remarks	Conditions	V _{DD} [V]	min.	typ.	max.	unit			
HALT mode consumption current	IDDHALT(8)	V _{DD} 1	HALT mode FsX'tal=32.768kHz crystal oscillation mode	5.0		25	69				
(Note 9-1) (Note 9-2)			System clock set to 32.768kHz side Internal RC oscillation stopped Frequency variable RC	3.3		8.5	29				
						oscillation stopped. • 1/2 frequency division ratio • Ta=-10 to +50°C	2.5		4.2	15	
HOLD mode	IDDHOLD(1)		HOLD mode	1.8 to 5.5		0.04	30				
consumption current			CF1=V _{DD} or open (External clock mode)	1.8 to 3.6		0.02	21				
(Note 9-1)	IDDHOLD(2)	1	HOLD mode	5.0		0.04	2.3				
(Note 9-2)			• CF1=V _{DD} or open	3.3		0.02	1.5				
			(External clock mode) • Ta=-10 to 50°C	2.5		0.017	1.2				
	IDDHOLD(3)		HOLD mode • CF1=V _{DD} or open	1.8 to 5.5		2.2	34	μΑ			
			(External clock mode) • LVD option selected	1.8 to 3.6		1.7	24				
	IDDHOLD(4)		HOLD mode • CF1=V _{DD} or open	5.0		2.2	5.4				
			(External clock mode)	3.3		1.7	3.8				
			• Ta=-10 to 50°C • LVD option selected	2.5		1.5	3.3				
Timer HOLD	IDDHOLD(5)		Timer HOLD mode	1.8 to 5.5		22	106				
mode consumption			FsX'tal=32.768kHz crystal oscillation mode	1.8 to 3.6		7.5	45				
current	IDDHOLD(6)	1	Timer HOLD mode	5.0		22	62				
(Note 9-1)			• FsX'tal=32.768kHz	3.3		7.5	23				
(Note 9-2)			• Ta=-10 to 50°C	2.5		2.9	12				

Note 9-1: Values of the consumption current do not include current that flows into the output transistors and internal pull-up resistors.

Note 9-2: The consumption current values do not include operational current of LVD function if not specified.

10. F-ROM Programming Characteristics at $Ta = +10 \text{ to } +55^{\circ}\text{C}$, $V_{SS}1 = V_{SS}2 = 0\text{V}$

Parameter	Symbol	Pin/Remarks	Conditions	Specificati			cation	
Parameter	Cymbol	i iii/i Celliaiks	Conditions	V _{DD} [V]	min.	typ.	max.	unit
Onboard programming current	IDDFW	V _{DD} 1	Only current of the Flash block.	2.2 to 5.5		5	10	mA
Programming	tFW(1)		Erasing time	2.2 to E.E.		20	30	ms
time	tFW(2)		Programming time	2.2 to 5.5		40	60	μs

11. UART (Full Duplex) Operating Conditions at Ta = -40 to +85°C, $V_{SS}1 = V_{SS}2 = 0V$

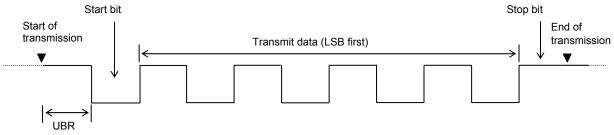
Parameter	Cymphol	Pin/Remarks	Conditions		Specification				
	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min.	typ.	max.	unit	
Transfer rate	UBR	P20, P21		1.8 to 5.5	16/3		8192/3	tCYC	

Data length : 7/8/9 bits (LSB first)

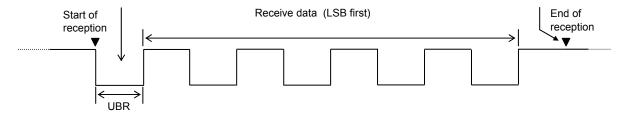
Stop bits : 1 bit(2-bit in continuous data transmission)

Parity bits : None

Example of Continuous 8-bit Data Transmission Mode Processing (First Transmit Data=55H)



Example of Continuous 8-bit Data Reception Mode Processing (First Receive Data=55H)



Characteristics of a Sample Main System Clock Oscillation Circuit

Given below are the characteristics of a sample main system clock oscillation circuit that are measured using our company-designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 1 Characteristics of a Sample Main System Clock Oscillator Circuit with a Ceramic Oscillator

Nominal	Vendor Name	Oscillator Name	Circuit Constant				Operating Oscillat Voltage Stabilizatio			Remarks
Frequency			C1	C2	Rf	Rd	Range	Тур	Max	Remarks
			[pF]	[pF]	[Ω]	[Ω]	[V]	[ms]	[ms]	
12MHz	MURATA	CSTCE12M0G52-R0	(10)	(10)	Open	470	2.7 to 3.6	0.1	0.5	Internal C1, C2
IZIVITIZ			(10)	(10)	Open	680	3.6 to 5.5	0.1	0.5	
10MHz		CSTCE10M0G52-R0	(10)	(10)	Open	680	2.2 to 3.6	0.1	0.5	
			(10)	(10)	Open	1.0k	3.6 to 5.5	0.1	0.5	
		CSTLS10M0G53-B0	(15)	(15)	Open	680	2.2 to 3.6	0.1	0.5	
			(15)	(15)	Open	680	3.6 to 5.5	0.1	0.5	
4MHz		CSTCR4M00G53-R0	(15)	(15)	Open	2.2k	1.8 to 2.7	0.2	0.6	
			(15)	(15)	Open	3.3k	2.7 to 5.5	0.2	0.6	
		CSTLS4M00G53-B0	(15)	(15)	Open	2.2k	1.8 to 2.7	0.2	0.6	
			(15)	(15)	Open	3.3k	2.7 to 5.5	0.2	0.6	

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized after V_{DD} goes above the operating voltage lower limit (see Figure 4).

Characteristics of a Sample Subsystem Clock Oscillator Circuit

Given below are the characteristics of a sample subsystem clock oscillation circuit that are measured using our company-designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 2 Characteristics of a Sample Subsystem Clock Oscillator Circuit with a Crystal Oscillator

Nominal	Vendor Name	Oscillator Name	Circuit Constant				Operating Voltage	Oscillation Stabilization Time		Daniel
Frequency			C1	C2	Rf	Rd	Range	Тур	Max	Remarks
			[pF]	[pF]	$[\Omega]$	$[\Omega]$	[V]	[s]	[s]	
32.768kHz	EPSON TOYOCOM	MC-306	9	9	Open	330k	1.8 to 5.5	1.4	4.0	Applicable CL value = 7.0pF

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized after the instruction for starting the subclock oscillation circuit is executed and to the time interval that is required for the oscillation to get stabilized after the HOLD mode is reset (see Figure 4).

Note: The components that are involved in oscillation should be placed as close to the IC and to one another as possible because they are vulnerable to the influences of the circuit pattern.

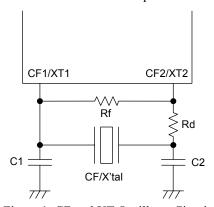
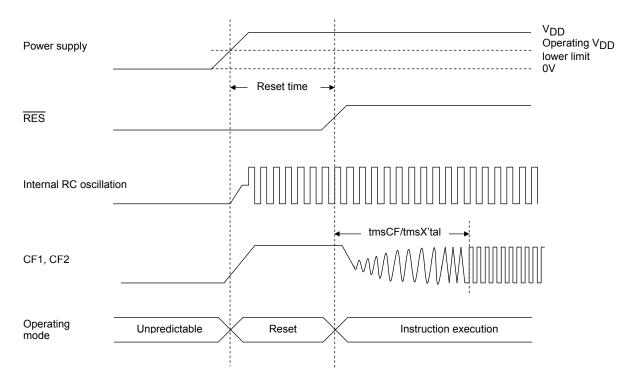


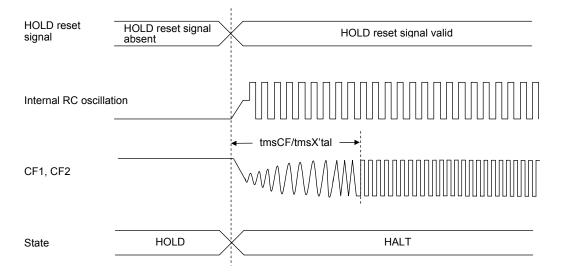
Figure 1 CF and XT Oscillator Circuit



Figure 2 AC Timing Measurement Point

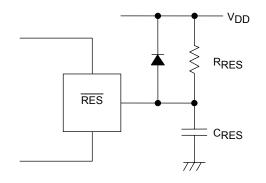


Reset Time and Oscillation Stabilization Time



HOLD Reset Signal and Oscillation Stabilization Time

Figure 3 Oscillation Stabilization Times



Note: External circuits for reset may vary depending on the usage of POR and LVD. Please refer to the user's manual for more information.

Figure 4 Reset Circuit

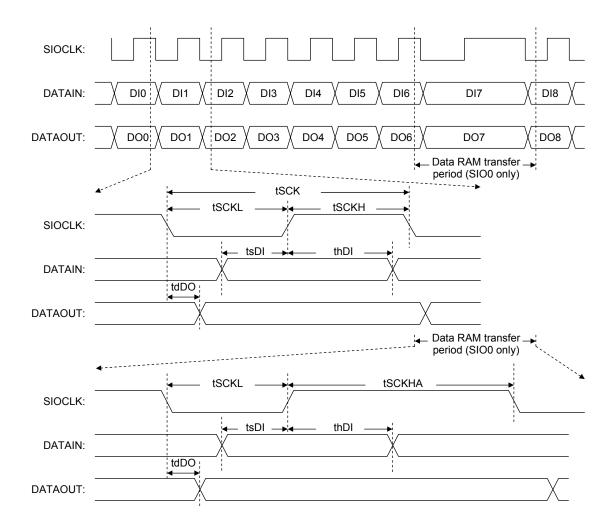


Figure 5 Serial I/O Output Waveforms

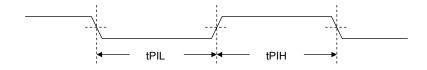


Figure 6 Pulse Input Timing Signal Waveform

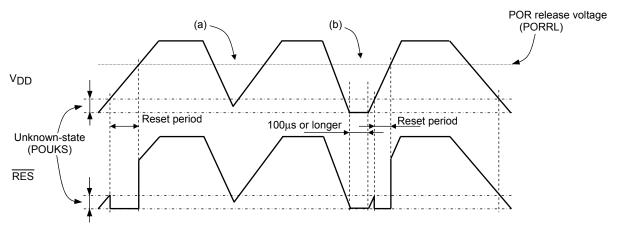


Figure 7 Waveform observed when only POR is used (LVD not used) (RESET pin: Pull-up resistor RRES only)

- The POR function generates a reset only when power is turned on starting at the VSS level.
- No stable reset will be generated if power is turned on again when the power level does not go down to the VSS level as shown in (a). If such a case is anticipated, use the LVD function together with the POR function or implement an external reset circuit.
- A reset is generated only when the power level goes down to the VSS level as shown in (b) and power is turned on again after this condition continues for 100µs or longer.

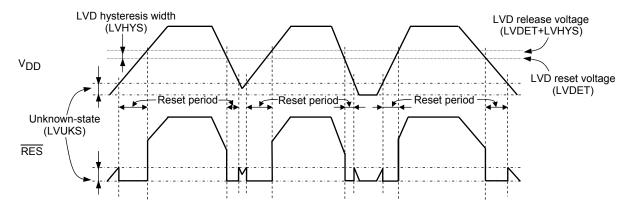


Figure 8 Waveform observed when both POR and LVD functions are used (RESET pin: Pull-up resistor R_{RES} only)

- Resets are generated both when power is turned on and when the power level lowers.
- A hysteresis width (LVHYS) is provided to prevent the repetitions of reset release and entry cycles near the detection level.

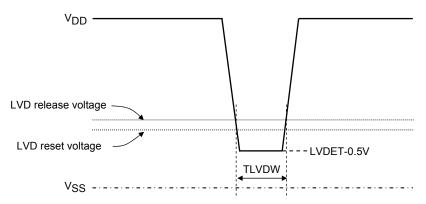


Figure 9 Low voltage detection minimum width (Example of momentary power loss / Voltage variation waveform)

ORDERING INFORMATION

Device	Package	Shipping (Qty / Packing)
LC87F2416AU-EB-2E	QFP36 (Pb-Free)	1250 / Tray JEDEC

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